



Material Content Data Sheet



Sales Product Name		ICE3BR0665J		Issued		24. January 2018		
MA#		MA000981102						
Package		PG-DIP-8-13		Weight*		557.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.709	1.02	1.02	10236	10236
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7705	
wire	non noble metal	copper	7440-50-8	174.475	31.28	32.10	312838	321024
	noble metal	gold	7440-57-5	0.280	0.05	0.05	502	502
	encapsulation	organic material	carbon black	1333-86-4	1.086	0.19		1948
encapsulation	plastics	epoxy resin	-	35.130	6.30		62989	
	inorganic material	silicondioxide	60676-86-0	325.947	58.46	64.95	584432	649369
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13440	13440
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1427	1427
glue	plastics	epoxy resin	-	0.335	0.06		600	
	noble metal	silver	7440-22-4	1.898	0.34	0.40	3402	4002
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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